

**Amendments to the Claims:** This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims:

1. (Currently Amended) A method of manufacturing a circuit board, comprising:

a step of superposing on a supporting member a pattern layer in which circuit pattern cavities are formed ~~in which~~ correspondence with a desired electroconductive circuit pattern, and  
~~which is formed of a conductor or an insulator;~~

a step of filling the circuit pattern cavities with an electroconductive material;

a step of removing the pattern layer from the supporting member after filling with the electroconductive material and thereby providing the electroconductive circuit pattern on the supporting member; and

a step of transferring into an insulating material the electroconductive circuit pattern formed by filling the circuit pattern cavities with the electroconductive material.

2. (Original) The method according to claim 1, further comprising a step of forming a mold release layer on the supporting member before the pattern layer is superposed on the supporting member, wherein said step of superposing the pattern layer on the supporting member comprises a step of superposing the pattern layer on the mold release layer so that the pattern layer is not combined with the mold release layer.

3. (Original) The method according to claim 1, wherein the circuit pattern cavities are filled with an electroconductive material different from the conductor by electroplating.

4. (Original) The method according to claim 1, wherein the circuit pattern cavities are filled with the electroconductive material by application or printing.

5. (Original) The method according to claim 4, wherein the electroconductive material is an electroconductive paste.

6. (Previously Presented) The method according to claim 1, wherein the pattern layer is formed of a photoresist.

7. (Original) The method according to claim 1, further comprising a step of forming a through hole in a predetermined portion of the insulating material and filling the through holes with an electroconductive paste, wherein said step of transferring the circuit pattern comprises a step of transferring circuit patterns into two surfaces of the insulating material, and wherein the predetermined portion is a portion for connection of at least part of the circuit patterns transferred into the two surfaces of the insulating material.

8. (Withdrawn) A communication appliance comprising:

a transmitter or a receiver having a high-frequency circuit including a circuit element mounted on a circuit board; and

an antenna;

wherein said circuit board is manufactured by the method according to claim 1.

9. (Previously Presented) The method according to claim 3, wherein the pattern layer is formed of a photoresist.